

## PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>JoungIn Yang</td><td>06/27/2007</td></tr><tr><td>KeonTeak Kang</td><td>06/27/2007</td></tr><tr><td>YoungChul Kim</td><td>06/27/2007</td></tr><tr><td>ChoongBin Yim</td><td>06/27/2007</td></tr></tbody></table>	Name	Execution Date	JoungIn Yang	06/27/2007	KeonTeak Kang	06/27/2007	YoungChul Kim	06/27/2007	ChoongBin Yim	06/27/2007	
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JoungIn Yang	06/27/2007										
KeonTeak Kang	06/27/2007										
YoungChul Kim	06/27/2007										
ChoongBin Yim	06/27/2007										
RECEIVING PARTY DATA											
Name:	STATS ChipPAC, Ltd.										
Street Address:	5 Yishun Street 23										
City:	Singapore										
State/Country:	SINGAPORE										
Postal Code:	768442										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11771086</td></tr></tbody></table>	Property Type	Number	Application Number:	11771086							
Property Type	Number										
Application Number:	11771086										
CORRESPONDENCE DATA											
Fax Number:	(602)229-5690										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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ATTORNEY DOCKET NUMBER:	125155.00027										
NAME OF SUBMITTER:	Robert D. Atkins										

CH \$40.00 11771086

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PATENT  
REEL: 019498 FRAME: 0638

Total Attachments: 4

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**PATENT**

**REEL: 019498 FRAME: 0639**

## ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JOUNGIN YANG of Kyongkido, South Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled STACKABLE PACKAGE BY USING INTERNAL STACKING MODULES, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00027, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

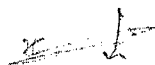
I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

  
\_\_\_\_\_  
Signature for JOUNGIN YANG

Witnessed on this date: June. 27. 2007.

Signature of Witness:   
\_\_\_\_\_

Printed Name of Witness: Dong Sam. Park.

Address of Witness: 605-1003 Hansol-jugong APT Jeongja-dong  
Bundang-gu Seongnam-si Kyongkido Korea.

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## ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KEONTEAK KANG of Namyangju City, South Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled STACKABLE PACKAGE BY USING INTERNAL STACKING MODULES, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00027, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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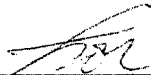
I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

\_\_\_\_\_  
Signature for KEONTEAK KANG

Witnessed on this date:

June. 27. 2007

Signature of Witness:



Printed Name of Witness:

Seungmin Lee

Address of Witness:

112-903 Pongnam APT Gyeongju 3-dong  
Namyangju. Seoul. Korea

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## ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, YOUNGCHUL KIM of Kyonggi-do, South Korea, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled STACKABLE PACKAGE BY USING INTERNAL STACKING MODULES, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00027, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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\_\_\_\_\_  
Signature for YOUNGCHUL KIM

Witnessed on this date:

Jun. 29th 2007

Signature of Witness:



Printed Name of Witness:

Myungkil Lee

Address of Witness:

386-20, 202 Seongnam-dong, Kyeonggi-do

Seoul, Korea 134-030

QBPHX\2100122.1

## ASSIGNMENT AND AGREEMENT

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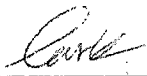
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\_\_\_\_\_  
Signature for CHOONGBIN YIM

Witnessed on this date:

Jun 27 2007

Signature of Witness:

  
\_\_\_\_\_

Printed Name of Witness:

Goo San Park

Address of Witness:

382 Dong San 4st. SungBuk Gun Seoul  
Republic of Korea

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